

This certificate is granted and awarded by the authority of the Nadcap Management Council to:

### Benchmark Electronics Tijuana S de RL de CV

Corredor Tijuana- Rosarito 2000 # 24702 Colonia Ejido Francisco Villa 2da Secc.
Tijuana, CP, BAJA CALIFORNIA 22236
Mexico

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturer's List (QML), to the revision in effect at the time of the audit for:

### Electronics - Printed Board Assemblies

Certificate Number: 9615236387 Expiration Date: 31 August 2026 Accreditation Length: 18 Months

**Jay Solomond** 

**Executive Vice President & Chief Operating Officer** 



#### SCOPE OF ACCREDITATION

#### **Electronics - Printed Board Assemblies**

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This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

#### AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION

## AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)

In-Process Verification / Inspection: AOI In-Process Verification / Inspection: X-Ray

Kitting

Moisture Sensitive Components and Materials

Secondary Assembly: Bonding

Secondary Assembly: Compliant Pin (Press Fit) Connector Installation

Secondary Assembly: Jumper Wire Installation Secondary Assembly: Stranded Wire Tinning Secondary Assembly: Wire Cutting & Stripping

#### AC7120/1 - Nadcap Audit Criteria for Circuit Card Assemblies Personnel Qualification

# AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

Electronic Component Preparation for Preassembly Process

Gold Removal Hand Soldering

Part Placement: Manual

## AC7120/3 - Plated Through Hole Technology (requires AC7120/2) (to be used on audits on/after 9 April 2017)

Selective Soldering
Wave Soldering

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# AC7120/4 Rev A - Surface Mount Technology (requires AC7120/2) (to be used on audits on/after 3 March 2019)

Preparation

Solder Paste Printing: Stencil Printing

AC7120/5 - Mixed Metallurgy for BGAs (requires AC7120/2 and AC7120/4) (to be used on audits on/after 9 April 2017)

AC7120/6 - Lead Free Soldering (requires AC7120/2) (to be used on audits on/after 9 April 2017)

AC7120/7 Rev A - Conformal Coating of Printed Board Assemblies (to be used on audits on/AFTER 05-Nov-2023)

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

AC7120/12 - Nadcap Audit Criteria for Depaneling (to be used on audits on/after 30 June 2019)

Mechanical Router Process

Programming

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